	Customer Initials:	Xilinx		Doc. Number : 104-K- 35861 A
Originated by:		Reviewed	by :	Cust Part# ML555 Rev 01 Polyclad 370 HR Material
	l avun In	nformation		
Layer Info zo Mode		Cu Copper	Prepreg	Dielectric
		Wt. Thickness	Qty. Style	Thickness Linewidth
1 S		h 0.0006		
	prepreg		1 106	0.0022
2 P		1 0.0012		
	Core			0.003
3 P		1 0.0012		
	prepreg		1 2113	0.0033
4 S		h 0.0006		
	Core			0.004
5 S		h 0.0006		
	prepreg		1 2113	0.0033
6 P		1 0.0012		
	Core			0.003
7 P		1 0.0012		
	prepreg	. 0.00.2	1 2113	0.0033
8 S		h 0.0006	1 2110	<u> </u>
	Core			0.004
9 S		h 0.0006		0.001
	prepreg	0.0000	1 2113	0.0033
10 P	p.op.og	1 0.0012	- 2113	0.0033
	Core	0.0012		0.003
11 P		1 0.0012		0.000
	prepreg	0.0012	1 2113	0.0033
12 S	proprog	h 0.0006	1 2113	0.0033
<u>"-</u> "	Core	0.0006		0.004
13 S		h 0.0006		0.004
١٠٠	prepreg	0.0006	1 2113	0.0033
14 P	Proprog	1 0.0012	1 2113	0.0003
	Core	1 0.0012		0.003
15 P		1 0.0012		[0.005]
	prepreg	1 0.0012	1 106	0.0022
16 S	picpicg	h 0.0006	100	0.0022
		0.0006		
Imp Layers 4, 5	, 8, 9, 12, & 13	3> 3.25 mil t	race / 4.75 mil space =	
P = Plane			Calculated Thickness Ov	
			Calculated Thickness Over I	
Lavun Configuration			Proce Configuration	
Layup Configuration Use caul plates. Polyclad 370 HR Material			Press Configuration Use Polyclad 370HR cycles.	
	Polyclad 370 HR	Material		les.

0100-F-2602 C 04/96 11/8/06